



NOTE: For the period of 10/1/2019 through 1/10/2020, due to a data irregularity in the customer impact lists, some indirect sales customers may not have received product change, product discontinuance, or product bulletin notices as expected through email. ON Semiconductor is taking the action to redistribute affected notices, with revised implementation dates conforming to external standards and ON Semiconductor's customer notification policies. This issue has been resolved. Questions related to this issue can be directed to PCN.Support@onsemi.com

Title of Change:	Update to PB22905Z - Datasheet Update to Package Drawing on AR0220
Effective date:	09 Mar 2020
Contact information:	Contact your local ON Semiconductor Sales Office or Philip.Lenox@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Other - Data sheet update/correction
Change Sub-Category(s):	Datasheet/Product Doc change

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
None	None

Description and Purpose:

The case outline drawing will be updated for the AR0220AT. The change will have no impact on the form, fit or function of the part. This is a documentation update to correctly reflect the current material being shipped. The nominal package case outline dimensions will remain within the previously listed tolerances, with minor modifications made to improve accuracy of the drawing.

This update is being made due to additional information made available from our package vendor. The discrepancy between documentation and shipped material was determined, the appropriate update was made to correctly reflect the shipped part. There will be no change to delivered parts.

The two case outline drawing impacted are 503CH and 503BF:

1. For 503CH, there are two updates made.
 - a. Total thickness of package: Previously 1.65 mm, updated to 1.675 mm.
 - b. Height from the die to the bottom of the package: Previously 0.475 +/- 0.05 mm, updated to 0.500 +/- 0.05 mm.
2. For 503BF, three changes were made.
 - a. Maximum rotation angle: Previously 0.5°, updated to 0.7°.
 - b. Total thickness of package: Previously 1.65 mm, updated to 1.700 mm.
 - c. Height from the die to the bottom of the package: Previously 0.475 +/- 0.05 mm, updated to 0.500 +/- 0.05 mm.

No manufacturing site is affected by this change.

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

AR0220AT4R00XUEA1-TRBM	AR0220AT4B00XUEA2-TPBR	AR0220AT4B00XUEA2-TRBR
AR0220AT4C00XUEA2-DPBR	AR0220AT4C00XUEA2-DRBR	AR0220AT4C00XUEA2-VL-TPBR
AR0220AT4C00XUEA2-TPBR	AR0220AT4C00XUEA2-TRBR	AR0220AT4R00XUEA1-DPBM
AR0220AT4R00XUEA1-DRBM	AR0220AT4R00XUEA1-VL-TPBM	AR0220AT4R00XUEA1-TPBM
AR0220AT4B00XUD20	AR0220AT4R00XUEA2-DPBR	AR0220AT4R00XUEA2-DRBR
AR0220AT4R00XUEA2-VL-TPBR	AR0220AT4R00XUEA2-TPBR	AR0220AT4R00XUEA2-TRBR



AR0220AT4B00XUEA2-DPBR	AR0220AT4B00XUEA2-DRBR	AR0220AT4B00XUEA2-VL-TPBR
AR0220AT4B00XUEA2-DPBR-E	AR0220AT4B00XUEA2-DRBR-E	AR0220AT4B00XUEA2-VL-TPBR-E
AR0220AT4B00XUEA2-TPBR-E	AR0220AT4B00XUEA2-TRBR-E	AR0220AT4C00XUEA2-DPBR-E
AR0220AT4C00XUEA2-DRBR-E	AR0220AT4C00XUEA2-VL-TPBR-E	AR0220AT4C00XUEA2-TPBR-E
AR0220AT4C00XUEA2-TRBR-E	AR0220AT4B00XUD20-E	